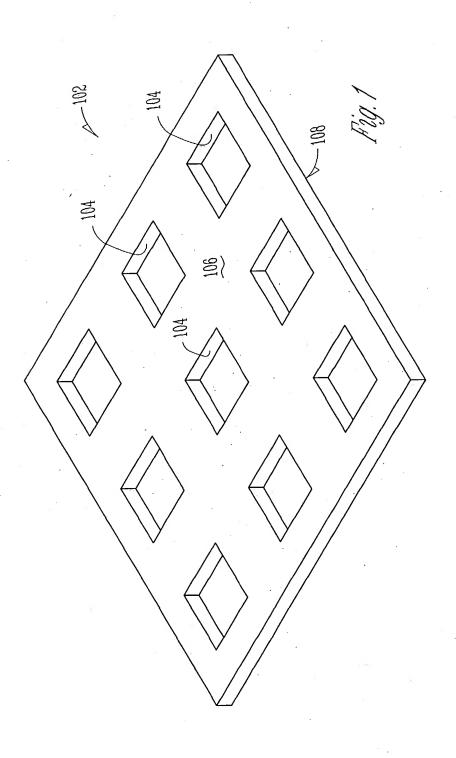
TITLE: INTEGRATED CORE MICROELECTRONIC PACKAGE INVENTORS NAME: Quat T. Vu et al. DOCKET NO.: 884.796US2



TITLE: INTEGRATED CORE MICROELECTRONIC PACKAGE INVENTORS NAME: Quat T. Vu et al.

DOCKET NO.: 884.796US2

2/8

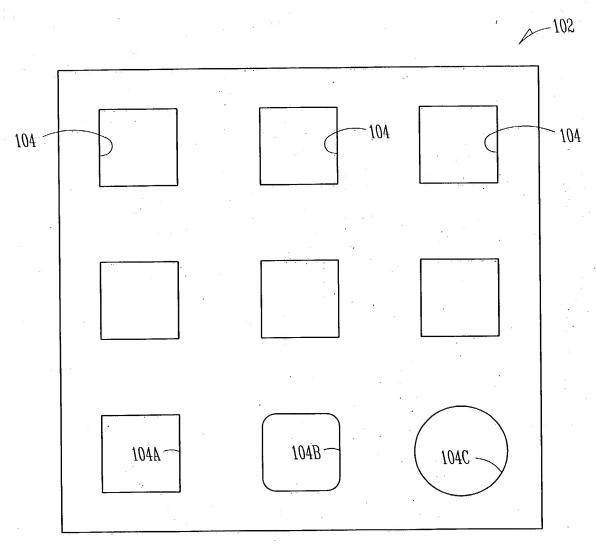


Fig.2

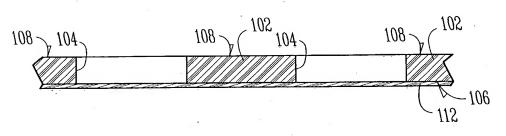
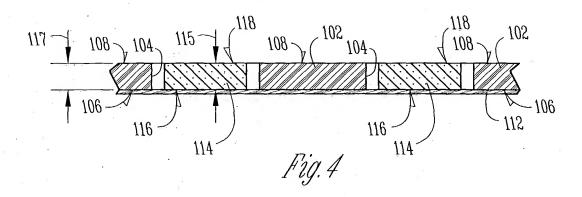
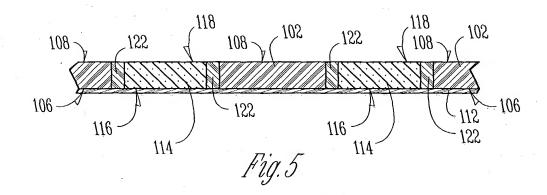


Fig. 3

TITLE: INTEGRATED CORE MICROELECTRONIC PACKAGE INVENTORS NAME: Quot T. Vu et al. DOCKET NO.: 884.796US2





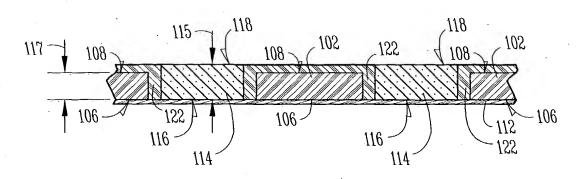
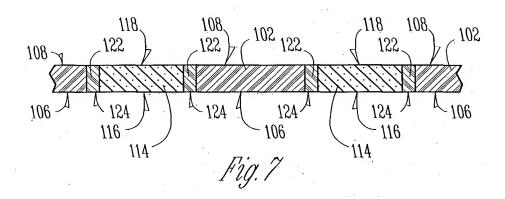


Fig. 6



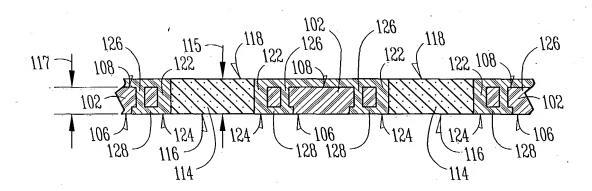
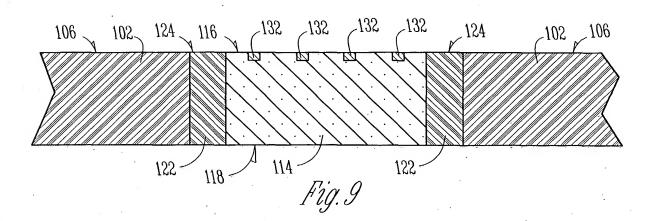
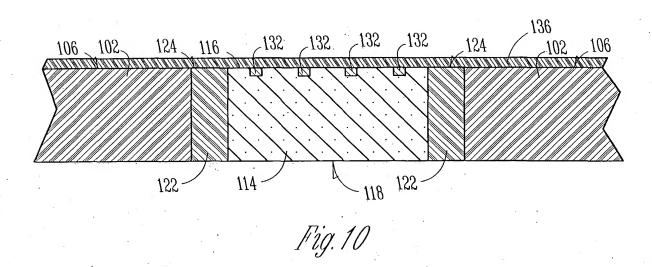


Fig. 8



TITLE: INTEGRATED CORE MICROELECTRONIC PACKAGE INVENTORS NAME: Quot T. Vu et al.

DOCKET NO.: 884.796U\$2



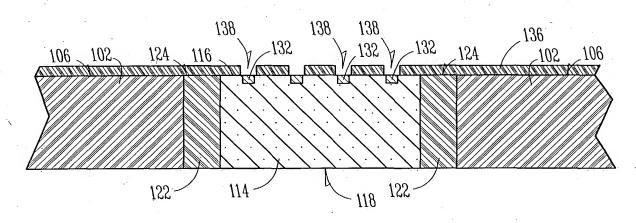


Fig. 11

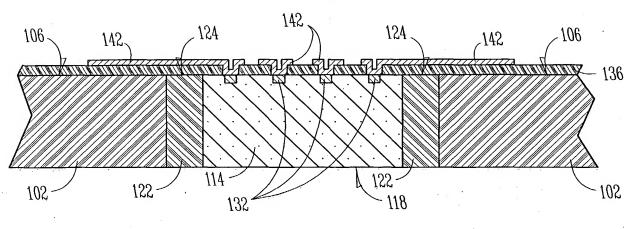
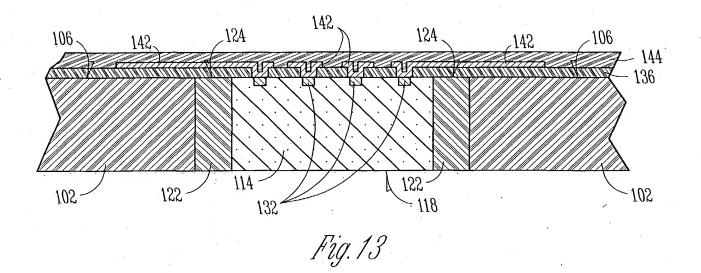


Fig. 12

TITLE: INTEGRATED CORE MICROELECTRONIC PACKAGE INVENTORS NAME: Quat T. Vu et ol. DOCKET NO.: 884.796US2



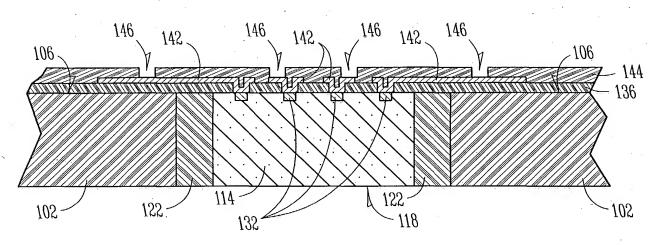


Fig. 14

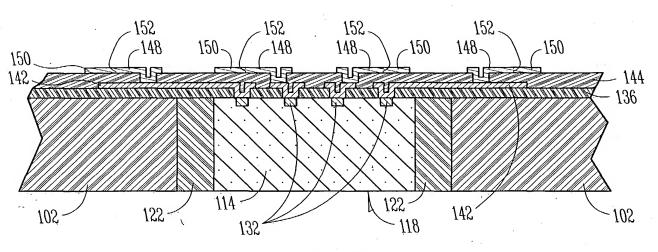


Fig. 15

TITLE: INTEGRATED CORE MICROELECTRONIC PACKAGE INVENTORS NAME: Quot T. Vu et al.

DOCKET NO.: 884.796US2

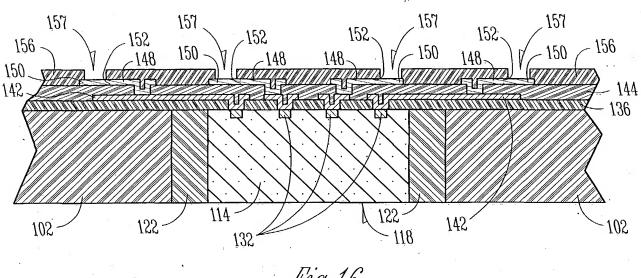
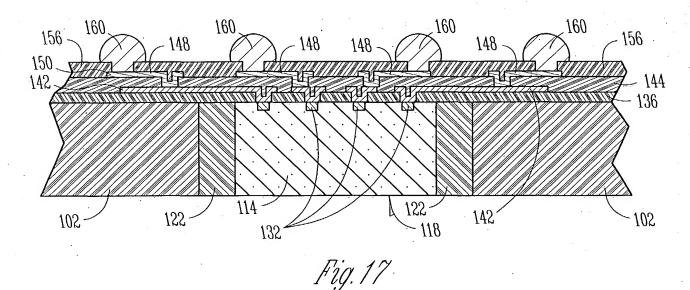


Fig. 16



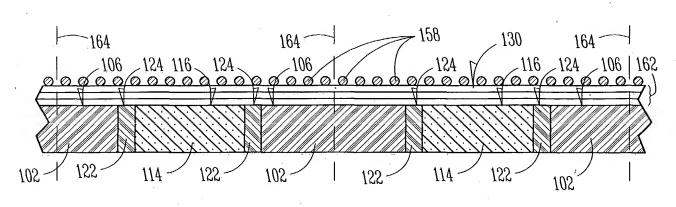
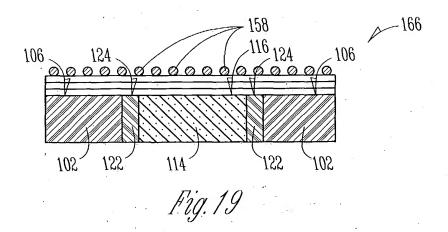


Fig. 18



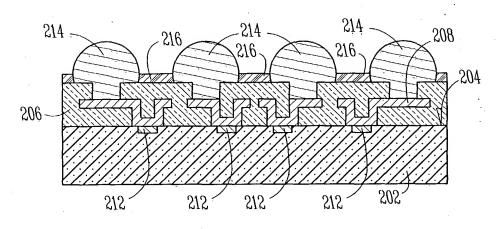


Fig.20 (Prior Art)

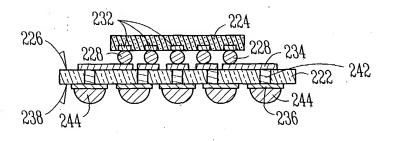


Fig.21 (Prior Art)